

N-Ch MOSFET

General Description

The WSD6040DN56 is the highest performance trench N-Ch MOSFET with extreme high cell density, which provide excellent R_{DSON} and gate charge for most of the synchronous buck converter applications .

The WSD6040DN56 meet the RoHS and Green Product requirement 100% EAS guaranteed with full function reliability approved.

Features

Lead Fre e an d Green Devices Available

(RoH SCom plia nt)

100% UIS + Rg Tested

Reliable and Rugged

Moistu re Sensitivity Level MSL1

(per JED EC J-STD-020D)

Product Summery

Bvdss	Rdson	Id
60V	17.5m Ω	36A

Applications

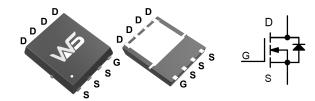
Secondary Side Synchronous Rectification

DC-DC Converter

Motor Control

Load Switching

DFN5x6A-8_EP Pin Configuration



Absolute Maximum Ratings @T_A=25℃ unless otherwise noted

Symbol	Parameter			Rating	Units	
V_{DS}	Drain-Source Voltage			60	V	
V _{GS}	Gate-Source Voltage			±20	V	
Ib	Continuous Drain Current $ \frac{\text{Tc=25}}{\text{Tc=10}} $		С	36	A	
			°C	22	A	
Ιp	Continuous Drain Current	T _A =25°C		8.4	A	
I D	T _A =10		°C	6.8	A	
I _{DM} ^a	Pulsed Drain Current	Tc=25°C		140	A	
P _D	Maximum Power Dissipation $\frac{Tc=2x}{Tc=10}$		С	37.8	W	
			°C	15.1		
PD	Maximum Power Dissipation $\frac{T_A=2:}{T_A=70}$		С	2.08	W	
			С	1.33		
I _{AS} c	Avalanche Current, Single pulse		L=0.5mH	16	A	
Eas c	Single Pulse Avalanche Energy		L=0.5mH	64	mJ	
Is	Diode Continuous Forward Current		Tc=25°C	18	A	
TJ	Maximum Junction Temperature			150	$^{\circ}\!\mathbb{C}$	
Tstg	Storage Temperature Range			-55 to 150	$^{\circ}$	
R ₀ JA ^b	Thermal Resistance Junction to ambient		Steady State	y State 60		
Rejc	Thermal Resistance-Junction to Case Ste		Steady State	3.3	°C/W	



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Note a: Pulse width limited by max. junction temperature.

Note b: Surface Mounted on 1in2 pad area.

Note c: UIS tested and pulse width limited by maximum junction temperature 150°C (initial temperature Tj=25°C).

Electrical Characteristics @TA=25°C unless otherwise noted

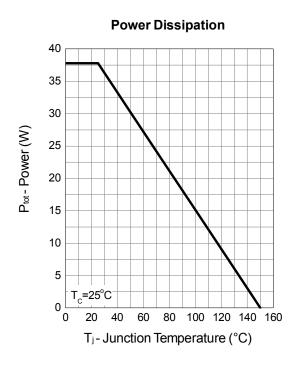
Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit				
Static										
V _{(BR)DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0V$, $I_D = 250 \mu A$	60			V				
Idss	Zero Gate Voltage Drain Current	$V_{DS} = 48 \text{ V}, V_{GS} = 0 \text{ V}$			1	μА				
		T _J =85°C			30					
Igss	Gate Leakage Current	$V_{GS} = \pm 20V, V_{DS} = 0V$			±100	nA				
On Character	istics									
$V_{\text{GS(TH)}}$	Gate Threshold Voltage	$V_{GS}=V_{DS},I_{DS}=250\mu A$	1	1.6	2.5	V				
R _{DS(on)} ^d	Dunin Common On state Besistance	$V_{GS} = 10V, I_D = 25A$		14	17.5	mΩ				
KDS(on)	Drain-Source On-state Resistance	$V_{GS} = 4.5V$, $I_D = 20A$		19	22	mΩ				
Switching										
Qg	Total Gate Charge	$V_{DS}=30V$		42		nC				
Qgs	Gate-Sour Charge	$V_{GS}=10V$		6.4		nC				
Qgd	Gate-Drain Charge	I _D =25A		9.6		nC				
td (on)	Turn-on Delay Time	V _{GEN} =10V		17		ns				
tr	Turn-on Rise Time	$V_{DD}=30V$ $I_{D}=1A$		9		ns				
td(off)	Turn-off Delay Time	$R_G=6\Omega$		58		ns				
tf	Turn-off Fall Time	RL=30Ω		14		ns				
Rg	Gat resistance	$V_{GS}=0V$, $V_{DS}=0V$, $f=1MHz$		1.5		Ω				
Dynamic										
Ciss	In Capacitance	V _{GS} =0V		2100		pF				
Coss	Out Capacitance	$V_{DS}=30V$		140		pF				
Crss	Reverse Transfer Capacitance	f=1MHz		100		pF				
Drain-Source	Diode Characteristics and Maximum	Ratings								
Is	Continuous Source Current	V-V-OV Force Current			18	A				
Isм	Pulsed Source Current3	V _G =V _D =0V , Force Current			35	A				
V _{SD} ^d	Diode Forward Voltage	$I_{SD} = 20A$, $V_{GS}=0V$		0.8	1.3	V				
trr	Reverse Recovery Time	I_{SD} =25A, dl_{SD}/dt =100A/ μ s		27		ns				
Qrr	Reverse Recovery Charge	1 _{SD} =23A, αι _{SD} /αι=100A/μS		33		nC				

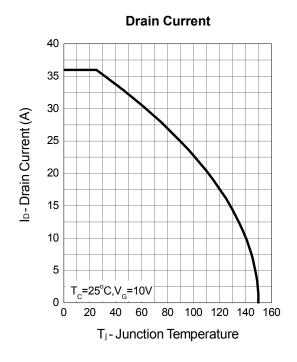
Note d: Pulse test; pulse width≤300µs, duty cycle≤2%.

Note e: Guaranteed by design, not subject to production testing.

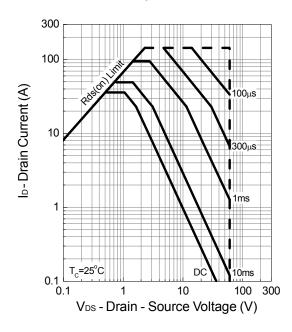


Typical Operating Characteristics

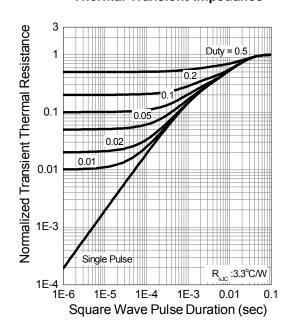




Safe Operation Area

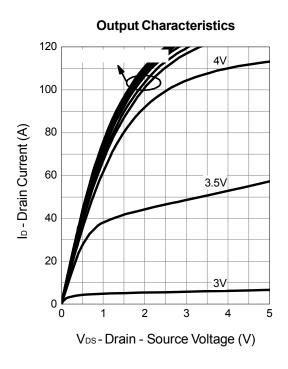


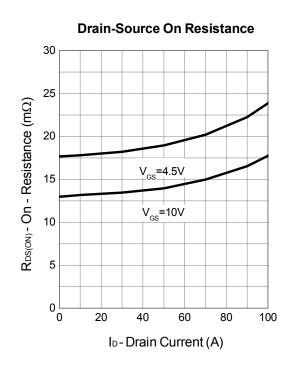
Thermal Transient Impedance

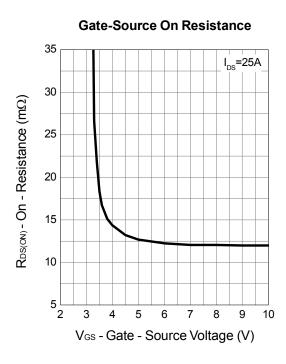


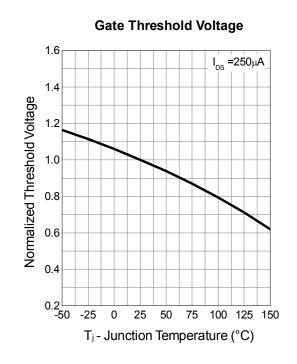


Typical Operating Characteristics (Cont.)



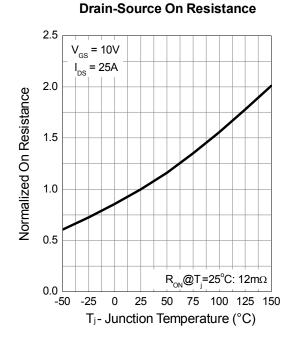




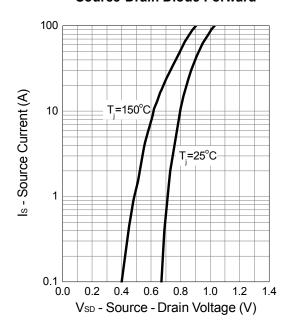




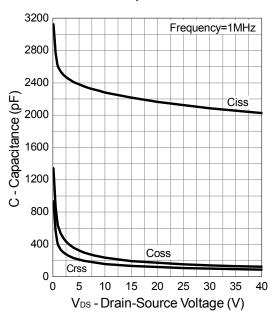
Typical Operating Characteristics (Cont.)



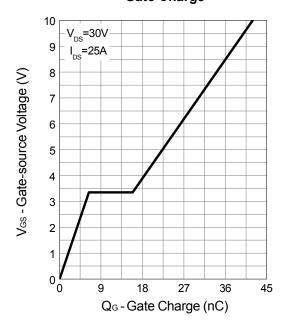
Source-Drain Diode Forward



Capacitance



Gate Charge





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